

PATENT ABSTRACTS OF JAPAN

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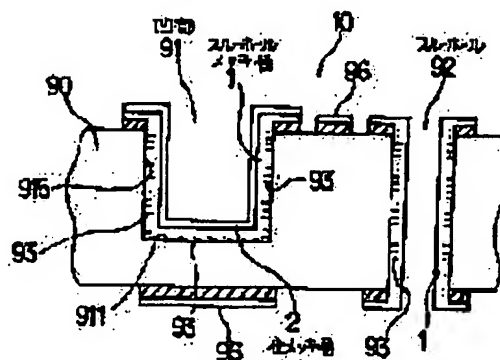
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(54) PRINTED WIRING BOARD

(57)Abstract:

PURPOSE: To provide a printed wiring board which has excellent humidity-proof characteristic and heat radiating characteristic and also facilitates wire bonding process and die bonding process.

CONSTITUTION: In a printed wiring board having a recess 91 for mounting electronic components and a through hole 92 on an organic resin substrate 90, the recess 91 and through hole 92 have a through hole plating layer 1 and the recess 91 has vertical wall surface formed by the counterboring process. Moreover, the outer most surface of the recess 91 is covered with gold plating layer 2.



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